N-Channel 1700V (D-S) SiC Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V) at T_J max.	1700	
$R_{DS(on)}$ at 25 °C (Ω)	V_{GS} = 18 V	0.600
Q_g (nC)	30	

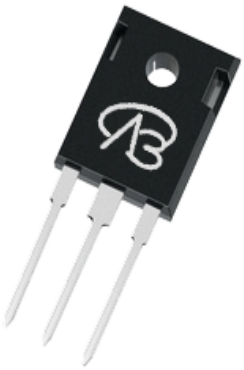
FEATURES

- Low figure-of-merit (FOM) R_{on} x Q_g
- Low input capacitance (C_{iss})
- Reduced switching and conduction losses
- Ultra low gate charge (Q_g)
- Avalanche energy rated (UIS)

RoHS

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- DC/DC converter



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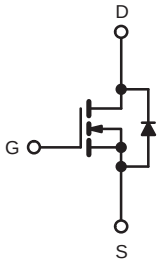

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T_C = 25 °C, unless otherwise noted)					
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-Source Voltage			V_{DS}	1700	V
Gate-Source Voltage			V_{GS}	-8 / +22	
Continuous Drain Current (T_J = 150 °C)	V_{GS} at 18 V	T_C = 25 °C	I_D	6	A
		T_C = 100 °C		4.2	
Pulsed Drain Current [a]			I_{DM}	12	
Linear Derating Factor				2.1	W/°C
Single Pulse Avalanche Energy [b]			E_{AS}	120	mJ
Maximum Power Dissipation			P_D	220	W
Operating Junction and Storage Temperature Range			T_J, T_{stg}	-55 to +175	°C
Drain-Source Voltage Slope	T_J = 125 °C		dV/dt	50	V/ns
Reverse Diode dV/dt [d]				15	
Soldering Recommendations (Peak Temperature) [c]	for 10 s			260	°C

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature.
b. V_{DD} = 100 V, starting T_J = 25 °C, L = 30mH, R_g = 25 Ω, I_{AS} = 3A.
c. 1.6 mm from case.
d. $I_{SD} \leq I_D$, dI/dt = 100 A/µs, starting T_J = 25 °C.

THERMAL RESISTANCE RATINGS				
PARAMETER	**SYMBOL**	**TYP.**	**MAX.**	**UNIT**
Maximum Junction-to-Ambient	R_{thJA}	-	40	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.68	

SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static						
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 1 mA	1700	-	-	V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to 25 °C, I_D = 1 mA	-	0.70	-	V/°C
Gate-Source Threshold Voltage (N)	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 10 mA	2.0	-	4.5	V
Gate-Source Leakage	I_{GSS}	V_{GS} = +22 V	-	-	100	nA
		V_{GS} = -10 V	-	-	-100	μA
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 1700V, V_{GS} = 0 V	-	10	-	μA
		V_{DS} = 1700 V, V_{GS} = 0 V, T_J = 125 °C	-	-	100	
Drain-Source On-State Resistance	$R_{DS(on)}$	V_{GS} = 18 V, I_D = 3A	-	0.600	-	Ω
Forward Transconductance	g_{fs}	V_{DS} = 0 V, I_D = 3 A	-	16	-	S
Dynamic						
Input Capacitance	C_{iss}	V_{GS} = 0 V, V_{DS} = 800 V, f = 1 MHz	-	500	-	pF
Output Capacitance	C_{oss}		-	18	-	
Reverse Transfer Capacitance	C_{rss}		-	5	-	
Effective Output Capacitance, Energy Related [a]	$C_{o(er)}$	V_{DS} = 0 V to 800 V, V_{GS} = 0 V	-	56	-	
Effective Output Capacitance, Time Related [b]	$C_{o(tr)}$		-	68	-	
Total Gate Charge	Q_g	V_{GS} = -5/18 V, I_D = 20A, V_{DS} = 800 V	-	30	-	nC
Gate-Source Charge	Q_{gs}		-	19	-	
Gate-Drain Charge	Q_{gd}		-	13	-	
Turn-On Delay Time	$t_{d(on)}$	V_{DD} = 800 V, I_D = 2A, V_{GS} = -5/18 V , R_g = 2 Ω	-	18	25	ns
Rise Time	t_r		-	12	25	
Turn-Off Delay Time	$t_{d(off)}$		-	3 0	-	
Fall Time	t_f		-	1 0	-	
Gate Input Resistance	R_g	f = 1 MHz, open drain	-	3.2	-	Ω
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 	-	-	6	A
Pulsed Diode Forward Current	I_{SM}		-	-	10	
Diode Forward Voltage	V_{SD}	T_J = 25 °C, I_S = 3 A, V_{GS} = 0	-	-	4.5	V
Reverse Recovery Time	t_{rr}	T_J = 25 °C, I_F = I_S = 3 A, dI/dt = 1000 A/μs, V_R = 800 V	-	40	-	ns
Reverse Recovery Charge	Q_{rr}		-	22	-	μC
Reverse Recovery Current	I_{RRM}		-	3	-	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}.

b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}.

Safe operating area Tc=25 ℃
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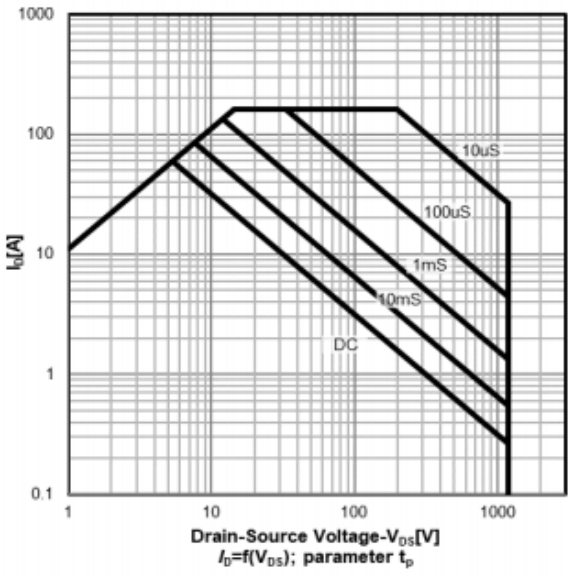
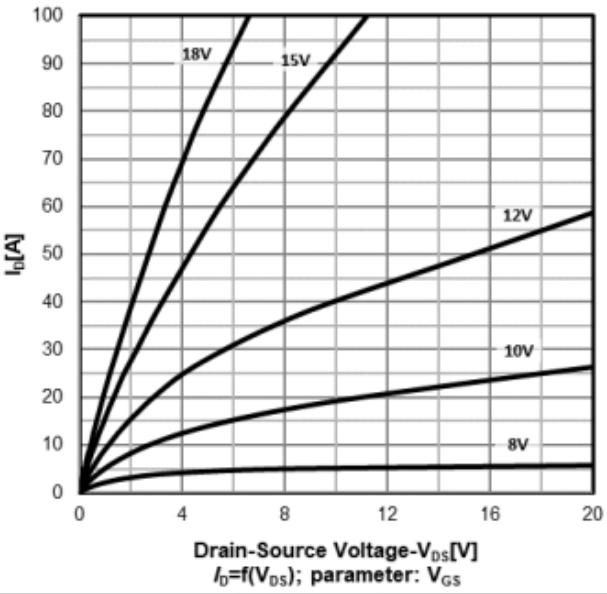
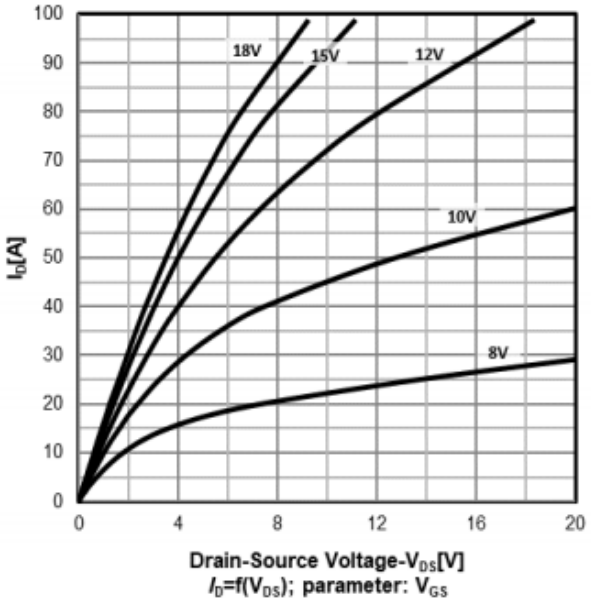


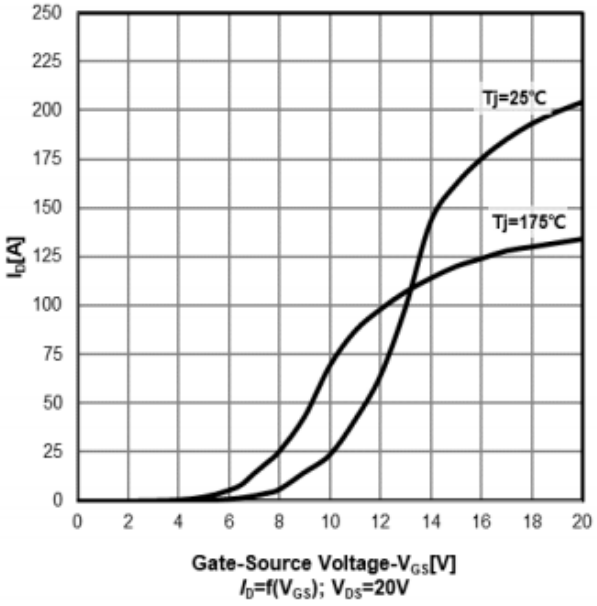
On-Region characteristics Tj=25 ℃



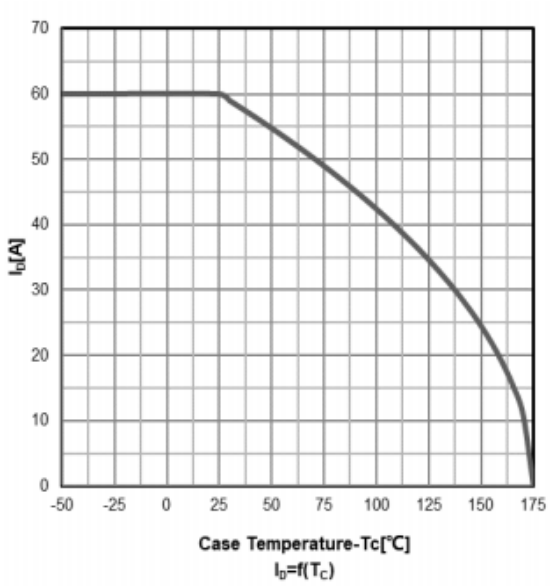
On-Region characteristics Tj=175 ℃



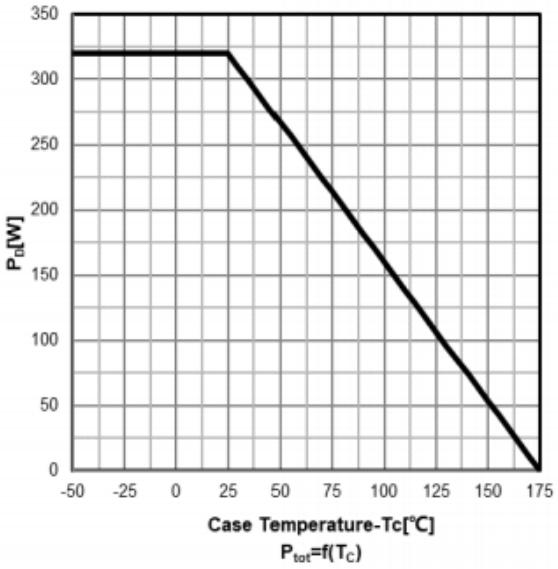
Transfer characteristics



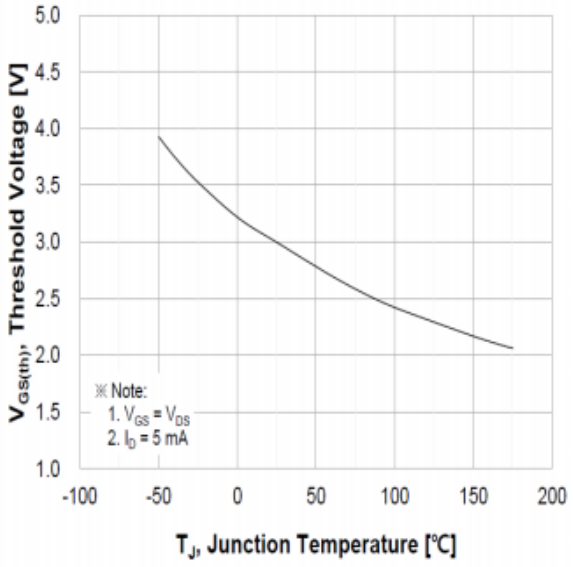
Drain current vs temperature



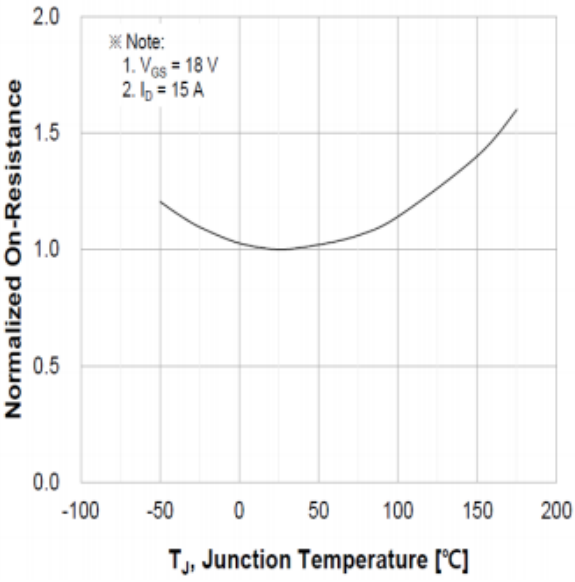
Power dissipation



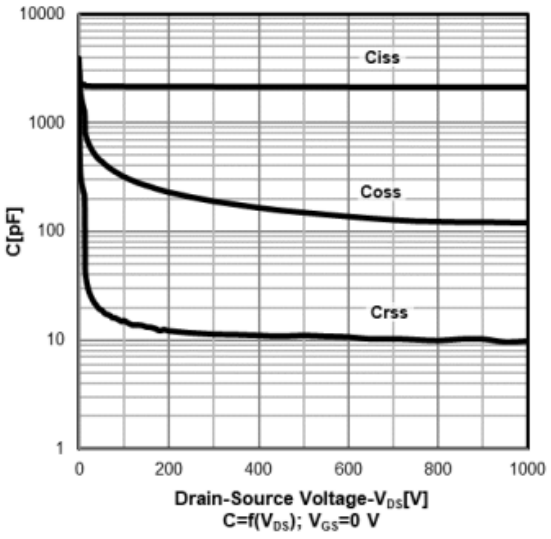
Threshold voltage vs temperature



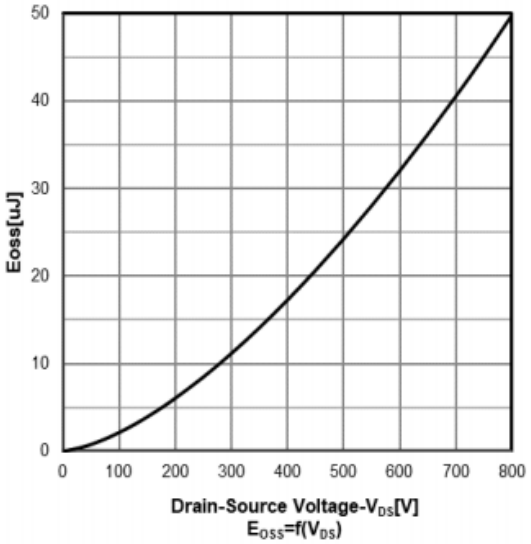
Normalized On-resistance vs temperature



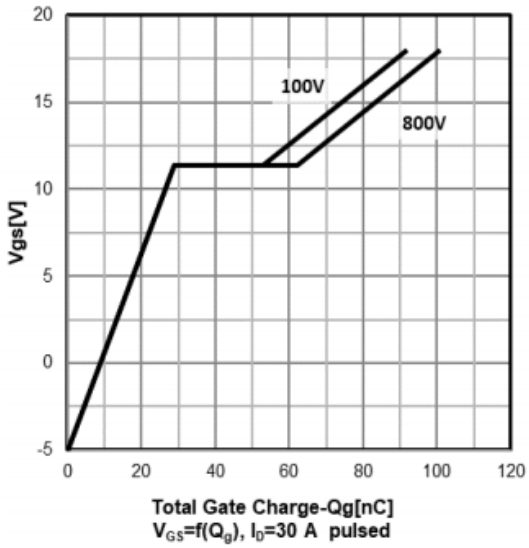
Typ. capacitances



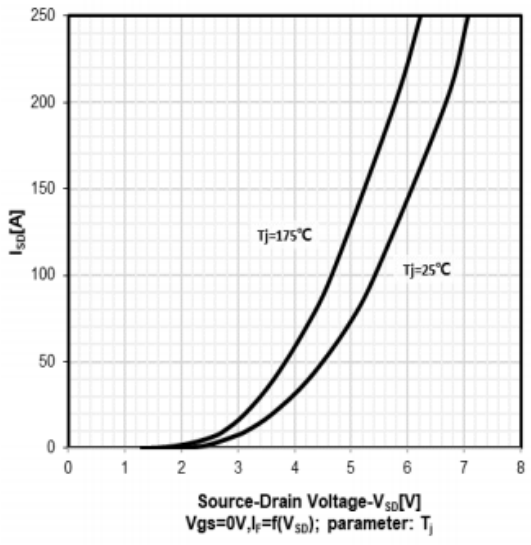
Coss stored energy



Typ. gate charge characteristics



Diode forward voltage characteristics
Tj=25 ℃/175 ℃



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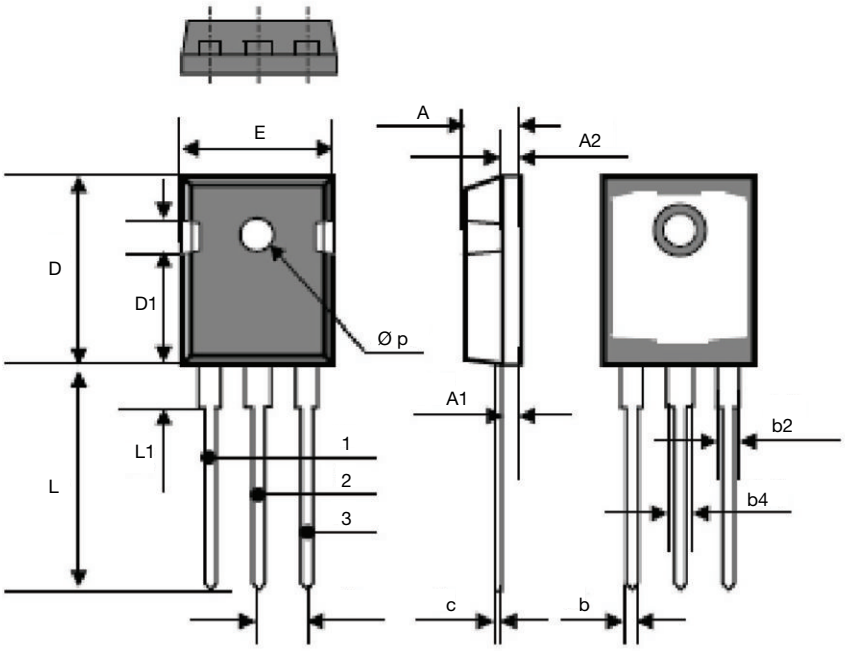

DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.70	5.31	0.185	0.209
A1	2.21	2.59	0.087	0.102
A2	1.50	2.49	0.059	0.098
b	0.99	1.40	0.039	0.055
b2	1.65	2.41	0.065	0.095
b4	2.59	3.43	0.102	0.135
c	0.61 BSC		0.024 BSC	
D	20.80	21.46	0.819	0.845
D1	3.68	5.49	0.145	0.216
(e)	5.46 BSC		0.215 BSC	
E	15.49	16.26	0.610	0.640
L	19.81	20.32	0.780	0.800
L1	4.06	4.50	0.160	0.177
Ø p	3.51	3.66	0.138	0.144

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